PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

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<tr>
<th>SUBMISSION TYPE:</th>
<th>NEW ASSIGNMENT</th>
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<td>NATURE OF CONVEYANCE:</td>
<td>ASSIGNMENT</td>
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CONVEYING PARTY DATA

<table>
<thead>
<tr>
<th>Name</th>
<th>Execution Date</th>
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</thead>
<tbody>
<tr>
<td>Naoyuki Koizumi</td>
<td>12/01/2008</td>
</tr>
<tr>
<td>Kiyoshi Oi</td>
<td>12/01/2008</td>
</tr>
<tr>
<td>Akihiko Tateiwa</td>
<td>12/01/2008</td>
</tr>
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RECEIVING PARTY DATA

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<tr>
<th>Name</th>
<th>SHINKO ELECTRIC INDUSTRIES CO., LTD.</th>
</tr>
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<tbody>
<tr>
<td>Street Address</td>
<td>80, Oshimada-machi</td>
</tr>
<tr>
<td>City</td>
<td>Nagano-shi, Nagano</td>
</tr>
<tr>
<td>State/Country</td>
<td>JAPAN</td>
</tr>
<tr>
<td>Postal Code</td>
<td>381-2287</td>
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PROPERTY NUMBERS Total: 1

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<td>Application Number</td>
<td>12330924</td>
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CORRESPONDENCE DATA

Fax Number: (216)566-9711

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 2165669700
Email: almasy@rankinhill.com

Correspondent Name: Rankin Hill and Clark LLP
Address Line 1: 38210 Glenn Avenue
Address Line 4: Willoughby, OHIO 44094

ATTORNEY DOCKET NUMBER: HKY-18725

NAME OF SUBMITTER: David E. Spaw

Total Attachments: 2
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ASSIGNMENT

WHEREAS, new and useful improvements have been made by the undersigned in

PACKAGE FOR SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING
THE SAME

that are the subject of an application for a U.S. Patent, (Application No. 12/330924, filed 12/09/2008), which application is further identified as Rankin, Hill & Clark LLP Docket No. HKY-18725.

WHEREAS, Shinko Electric Industries Co., Ltd., a corporation of Japan, and having a place of business at 80, Oshimada-machi, Nagano-shi, Nagano 381-2287, Japan, hereinafter referred to as "assignee", is desirous of acquiring all right, title, and interest throughout the world in, to, and under said improvements and inventions and patent rights therefor.

NOW, THEREFORE, be it known that, for valuable consideration, the receipt and sufficiency of which are hereby acknowledged, all right, title, and interest, in the United States and throughout the world, in, to and under said improvements and inventions and all patents, patent applications, patent rights, and inventor’s certificates thereof, therefor, and therein, including without limitation said application for patent in the United States, all divisions and continuations thereof, all patents which may be granted thereon, all reissues and extensions thereof, all right to sue for past infringement thereunder, all patents which may be granted for said improvements and inventions by states or nations other than the United States, or by other authority, entity, or organization, and all applications therefor, have been and are hereby sold, assigned, transferred, and delivered unto assignee, its successors and assigns; and it is covenanted and agreed by the undersigned, and for executors, administrators, and legal representatives of the undersigned, that at assignee’s request any and all applications, affidavits, assignments, and other instruments will be made, executed, and delivered as may be necessary, or desirable to secure for or vest in assignee, its successors or assigns, any improvement, inventions, right, title, interest, application, patent, patent right or other right or property covered by this assignment, and the United States Commissioner of Patents and Trademarks is hereby requested and authorized to issue any and all United States patents granted on any of said applications to assignee as owner of the entire right, title, and interest in, to, and under the same, and appropriately empowered officials of foreign countries are hereby authorized to issue any letters patent granted on any of said applications to assignee as owner of the entire right, title and interest in, to, and under the same.

The undersigned hereby grants the firm of Rankin, Hill & Clark LLP the power to insert on this assignment any identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.
IN WITNESS WHEREOF, this assignment has been executed below by the undersigned:

(1) Inventor Name (sole or joint): Naoyuki KOIZUMI
    Signature: Naoyuki Koizumi
    Today's Date: December 1, 2008
    Witness: 
    Witness: 

(2) Inventor Name (joint): Kiyoshi OI
    Signature: Kiyoshi Oi
    Today's Date: December 1, 2008
    Witness: 
    Witness: 

(3) Inventor Name (joint): Akihiko TATEIWA
    Signature: Akihiko Tateiwa
    Today's Date: December 1, 2008
    Witness: 
    Witness: 

(4) Inventor Name (joint): 
    Signature: 
    Today's Date: 
    Witness: 
    Witness: 